

## **Description**

The NTD4302T4G uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



#### **General Features**

V<sub>DS</sub> = 30V I<sub>D</sub> =50 A

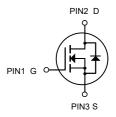
 $R_{DS(ON)}$  < 10m $\Omega$  @  $V_{GS}$ =10V

## **Application**

**Battery protection** 

Load switch

Uninterruptible power supply



N-Channel MOSFET

## **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
NTD4302T4G	TO-252-2L	HXY MOSFET	2500

## Absolute Maximum Ratings (T<sub>C</sub>=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units	
V <sub>D</sub> s	Drain-Source Voltage	30	V	
V <sub>G</sub> s	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	А	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	30	А	
Ідм	Pulsed Drain Current <sup>2</sup>	112	А	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	24.2	mJ	
las	Avalanche Current	22	А	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	37.5	W	
Тѕтс	Storage Temperature Range	-55 to 175	°C	
TJ	Operating Junction Temperature Range	-55 to 175	°C	
Reja	Thermal Resistance Junction-Ambient <sup>1</sup>	62	°C/W	
R <sub>θ</sub> JC	Thermal Resistance Junction-Case <sup>1</sup>	4 °CN		

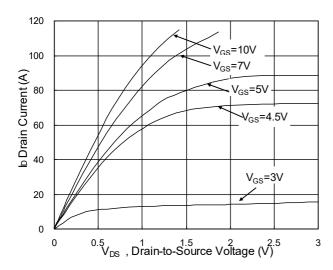
# Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVpss	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V	
△BV <sub>DSS</sub> /△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA		0.0193		V/°C	
RDS(ON)		V <sub>GS</sub> =10V , I <sub>D</sub> =30A		7.5	10		
	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		11	18	$\textbf{m}\Omega$	
VGS(th)	Gate Threshold Voltage		1.2		2.5	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-3.97		mV/°C	
1	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
IDSS		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		5 uA		uA	
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		34		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.8		Ω	
Qg	Total Gate Charge (4.5V)			9.8			
Qgs	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		4.2		nC	
Q <sub>gd</sub>	Gate-Drain Charge			3.6			
Td(on)	Turn-On Delay Time			4			
Tr	Rise Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V ,		8		ns	
Td(off)	Turn-Off Delay Time	R <sub>G</sub> =3.3		31			
Tf	Fall Time	I <sub>D</sub> =15A		4			
Ciss	Input Capacitance			940			
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		131		pF	
Crss	Reverse Transfer Capacitance			109		·	
Is	Continuous Source Current <sup>1,5</sup>				43	Α	
Іѕм	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			112	Α	
VsD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V	
t <sub>rr</sub>	Reverse Recovery Time	I=-20A - 41/44-400A/us		8.5		nS	
Qrr	Reverse Recovery Charge	IF=30A, dl/dt=100A/μs, T <sub>J</sub> =25°C		2.2		nC	

#### Note:

- 1 .The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leqq 300 us$  , duty cycle  $\leqq 2\%$
- 3 .The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =22A
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

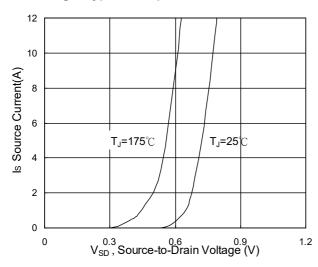


Fig.3 Forward Characteristics of Reverse

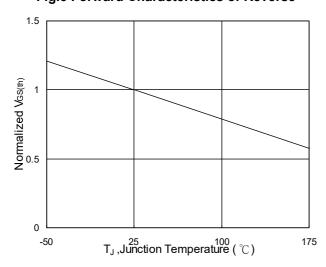


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs.  $T_{\text{J}}$ 

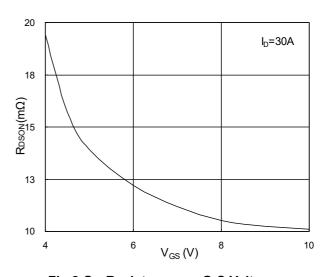


Fig.2 On-Resistance vs. G-S Voltage

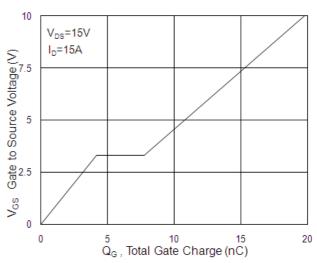


Fig.4 Gate-Charge Characteristics

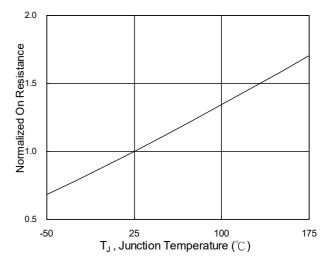
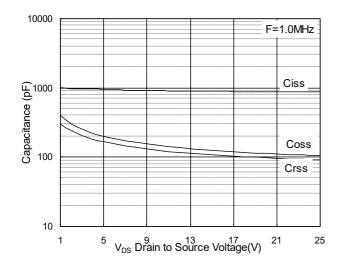


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



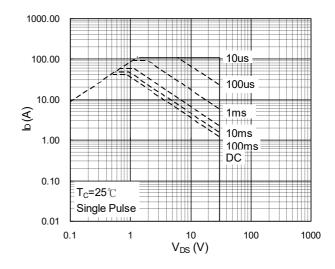


Fig.7 Capacitance

Fig.8 Safe Operating Area

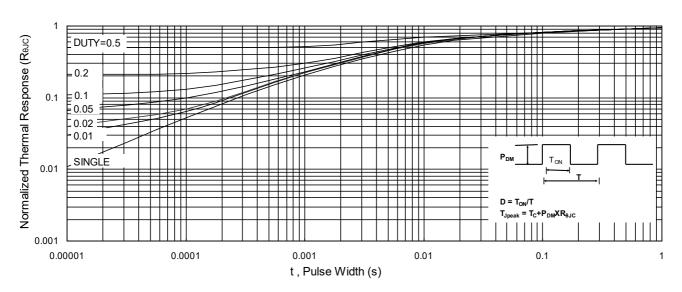


Fig.9 Normalized Maximum Transient Thermal Impedance

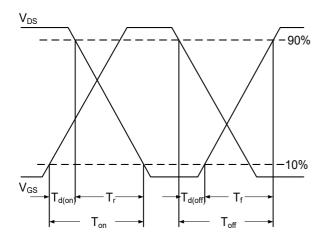


Fig.10 Switching Time Waveform

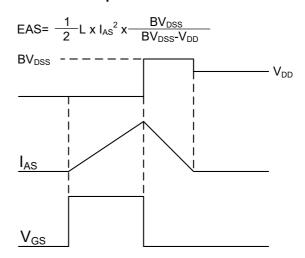
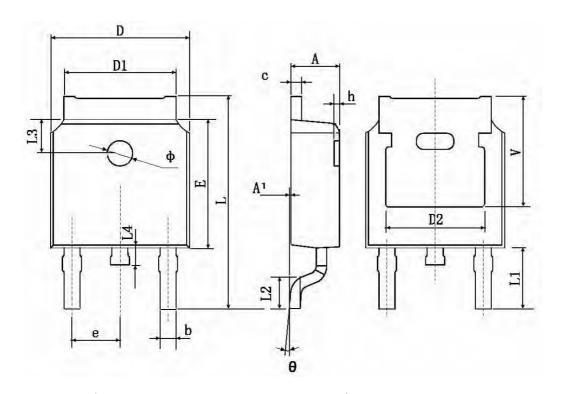


Fig.11 Unclamped Inductive Switching Waveform

# **TO-252-2L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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